

Filename: PMP8730REVB_bom.xls							
Date: 11/25/2013							
<b>PMP8730REVB BOM</b>							
COUNT	RefDes	Value	Description	SIZE	Part Number	MFR	AREA
1	C1	330pF	Capacitor, Ceramic, 50V, [temp], [tol]	0603	std	std	5650
1	C2	100nF	Capacitor, Ceramic, 16V	0603	std	std	5650
1	C3	220pF	Capacitor, Ceramic, 50V, [temp], [tol]	0603	std	std	5650
1	C4	22nF	Capacitor, Ceramic, 50V, [temp], [tol]	0603	std	std	5650
1	C5	1uF	Capacitor, Ceramic, 50V, X7R	0805	std	std	10560
1	C7	1u	Capacitor, Ceramic, 16V, X7R, 20%	0603	std	std	5650
2	C8	10uF	Capacitor, Ceramic, 50V, X7R	1210	Std	Kemet, Murata, AVX	83,600
1	C9	220pF	Capacitor, Ceramic, vvV, [temp], [tol]	0603	std	std	5650
	C10	10uF	Capacitor, Ceramic, 50V, X7R	1210	Std	Kemet, Murata, AVX	83,600
2	C11	10uF	Capacitor, Ceramic, 50V, X7R, 20%	1210	Std	std	83,600
	C12	10uF	Capacitor, Ceramic, 50V, X7R, 20%	1210	Std	std	83,600
1	C101	220pF	Capacitor, Ceramic, 220pF, 50V, COG, 0603	0603	Std	Std	5650
1	D1	B160	Diode, 1A, 60V	SMA	B160	Diodes Inc.	95000
1	D2	36V	Diode, Zener, 36-V, 225-mW	SOT23	BZX84C36	Vishay	13419
1	D3	6.2V	Diode, Zener, 6.2V	SOD-323	MMSZ5234BS-7-F	Diodes	195000
1	D4	5.1V	Diode, Zener, 5.1V	SOD-323	MMSZ5231BT1	Diodes	195000
1	D101	BAT54XV2T1	Diode, Schottky, 10 mA, 30 V	SOD523	BAT54XV2T1	On Semi	8125
2	J1	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST	141600
	J2	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST	141600
1	L1	150u	Inductor, SMT, 1.2-Adc, 251-milliohm	10mm x 10mm	7447714151	WE 1050 series	269,336
1	Q1	SQS460EN	MOSFET, NChan, 60V, 36millohm, 20nC	PWRPAK 1212	SQS460EN	Vishay	27200
1	Q2	MMBT2222A	Bipolar, NPN, 40V, 600mA	SOT23	MMBT2222ALT1	On Semi	14105
1	Q101	2N7002	MOSFET, N-ch, 60-V, 115-mA, 1.2-Ohms	SOT23	2N7002	Diodes	14105
1	R1	187k	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R2	14.3k	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R5	100k	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R6	10	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R7	4.7	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R8	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std	5650

1	R9	49.9	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R10	1k	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R11	0.1	Resistor, Chip, 1W, 5%	1206	STD	STD	35100
1	R14	3.48	Resistor, Chip 1/4 watt, ±1%	1206	STD	STD	20,000
2	R16	20k	Resistor, Chip, 1/16W, 1%	0805	Std	Std	10560
1	R17	1Meg	Resistor, Chip, 1/16W, 1%	0805	Std	Std	10560
	R18	20k	Resistor, Chip, 1/16W, 1%	0805	Std	Std	10560
1	R101	1k	Resistor, Chip, 1k, 1%, 0603	0603	Std	Std	5650
3	TP1	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone	10
2	TP2	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone	10
2	TP4	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone	10
1	TP5	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone	10
1	TP7	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone	10
	TP8	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone	10
	TP10	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone	10
	TP11	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone	10
	TP101	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone	10
1	U1	TPS40210DGQ	IC, Low Cost Non-Synchronous Boost Ctrl	DGQ10	TPS40210DGQ	TI	26780
Notes:	1. These assemblies are ESD sensitive, ESD precautions shall be observed.						
	2. These assemblies must be clean and free from flux and all contaminants.						
	Use of no clean flux is not acceptable.						
	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.						
	4. Ref designators marked with an asterisk (***) cannot be substituted.						
	All other components can be substituted with equivalent MFG's components.						

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